



Material Content Data Sheet



Sales Product Name		BSD314SPE H6327		Issued		20. July 2018		
MA#		MA001627124						
Package		PG-SOT363-6-6		Weight*		6.68 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.003	0.05		472	
	noble metal	gold	7440-57-5	0.012	0.18		1832	
	inorganic material	silicon	7440-21-3	0.187	2.79	3.02	27947	30251
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		99	
	non noble metal	titanium	7440-32-6	0.003	0.05		493	
	non noble metal	chromium	7440-47-3	0.010	0.15		1478	
	non noble metal	copper	7440-50-8	3.275	49.06	49.27	490695	492765
wire	non noble metal	copper	7440-50-8	0.048	0.72	0.72	7158	7158
encapsulation	organic material	carbon black	1333-86-4	0.028	0.43		4264	
	plastics	epoxy resin	-	0.612	9.17		91682	
	inorganic material	silicondioxide	60676-86-0	2.206	33.05	42.65	330482	426428
leadfinish	non noble metal	tin	7440-31-5	0.213	3.19	3.19	31944	31944
plating	noble metal	silver	7440-22-4	0.076	1.15	1.15	11454	11454
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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